

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6653053

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEIJUN WANG	04/12/2021
HONG LIN	04/12/2021
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17284849
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ATTORNEY DOCKET NUMBER:	TC21030033US
NAME OF SUBMITTER:	YUAN R. LI
SIGNATURE:	/Yuan R. Li/
DATE SIGNED:	04/13/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
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ASSIGNMENT AND DECLARATION FOR UTILITY PATENT APPLICATION

ASSIGNMENT:

WHEREAS I/We, the below named inventor(s), (hereinafter referred to as Assignor(s)), of a claimed invention in an application for United States Letters Patent entitled:

FORMATION METHOD OF SEMICONDUCTOR STRUCTURE

filed herewith; and

WHEREAS, SHANGHAI IC R&D CENTER CO., LTD.
a corporation of P.R. China

whose post office address is No.497, Gaosi Road, Zhangjiang High-Tech Park, Pudong, Shanghai, China 201210

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Director of the United States Patent and Trademark Office to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request that the attorneys having Power of Attorney in this application, insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known.

DECLARATION OF INVENTOR(S)

As a named inventor below, I hereby declare that: (1) This declaration is directed to the above-identified application; (2) the above-identified application was made or authorized to be made by me; (3) my residence and mailing address are as stated below next to my name; and (4) I believe I am an original inventor or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statements made in this declaration are punishable by fine or imprisonment of not more than five (5) years, or both, under section 1001 of Title 18 of the United States Code.

As a below named inventor, I have reviewed and understand the contents of the application, including the claims, and am aware of the duty to disclose to the USPTO all information known to me to be material to patentability as defined in 37C.F.R. § 1.56.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

1. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
WANG, Weijun	<i>WANG, Weijun</i>	
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2. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
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